Lattice Semiconductor Corporation - LCMXO2280E-4TN100C Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	285
Number of Logic Elements/Cells	2280
Total RAM Bits	28262
Number of I/O	73
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	100-LQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo2280e-4tn100c

The devices use look-up tables (LUTs) and embedded block memories traditionally associated with FPGAs for flexible and efficient logic implementation. Through non-volatile technology, the devices provide the single-chip, high-security, instant-on capabilities traditionally associated with CPLDs. Finally, advanced process technology and careful design will provide the high pin-to-pin performance also associated with CPLDs.

The ispLEVER® design tools from Lattice allow complex designs to be efficiently implemented using the MachXO family of devices. Popular logic synthesis tools provide synthesis library support for MachXO. The ispLEVER tools use the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the MachXO device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

sysCLOCK Phase Locked Loops (PLLs)

The MachXO1200 and MachXO2280 provide PLL support. The source of the PLL input divider can come from an external pin or from internal routing. There are four sources of feedback signals to the feedback divider: from CLKINTFB (internal feedback port), from the global clock nets, from the output of the post scalar divider, and from the routing (or from an external pin). There is a PLL_LOCK signal to indicate that the PLL has locked on to the input clock signal. Figure 2-10 shows the sysCLOCK PLL diagram.

The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the t_{LOCK} parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider, and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

Figure 2-10. PLL Diagram

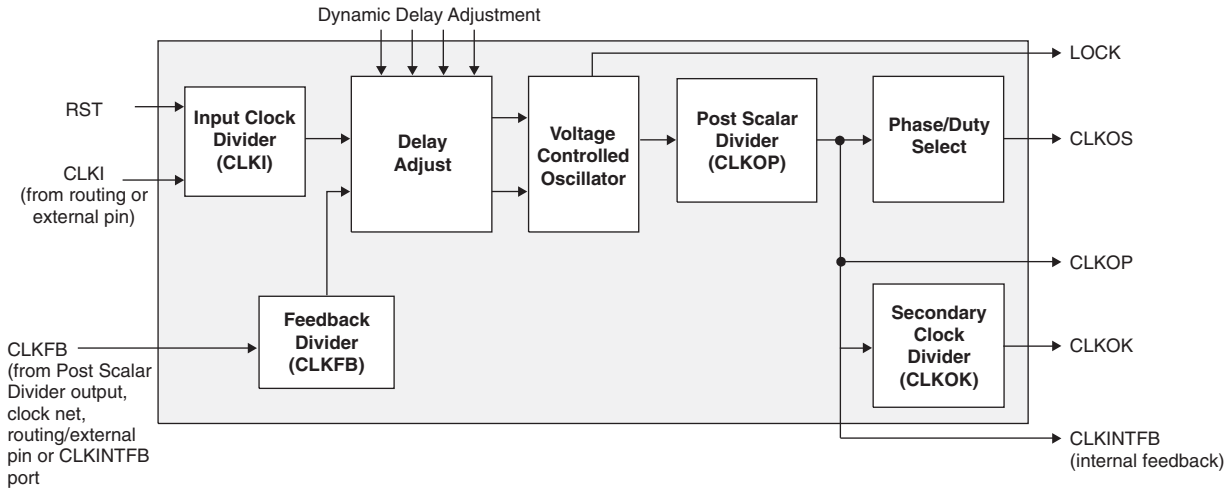
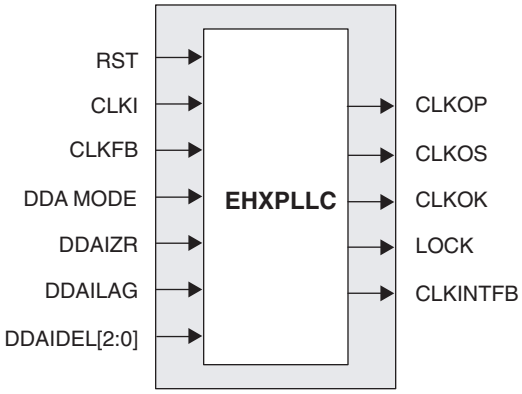


Figure 2-11 shows the available macros for the PLL. Table 2-5 provides signal description of the PLL Block.

Figure 2-11. PLL Primitive



of the devices also support differential input buffers. PCI clamps are available on the top Bank I/O buffers. The PCI clamp is enabled after V_{CC}, V_{CCAUX}, and V_{CCIO} are at valid operating levels and the device has been configured.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

2. **Left and Right sysIO Buffer Pairs**
The sysIO buffer pairs in the left and right Banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (supporting ratioed and absolute input levels). The devices also have a differential driver per output pair. The referenced input buffer can also be configured as a differential input buffer. In these Banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

Typical I/O Behavior During Power-up

The internal power-on-reset (POR) signal is deactivated when V_{CC} and V_{CCAUX} have reached satisfactory levels. After the POR signal is deactivated, the FPGA core logic becomes active. It is the user’s responsibility to ensure that all V_{CCIO} Banks are active with valid input logic levels to properly control the output logic states of all the I/O Banks that are critical to the application. The default configuration of the I/O pins in a blank device is tri-state with a weak pull-up to VCCIO. The I/O pins will maintain the blank configuration until VCC, VCCAUX and VCCIO have reached satisfactory levels at which time the I/Os will take on the user-configured settings.

The V_{CC} and V_{CCAUX} supply the power to the FPGA core fabric, whereas the V_{CCIO} supplies power to the I/O buffers. In order to simplify system design while providing consistent and predictable I/O behavior, the I/O buffers should be powered up along with the FPGA core fabric. Therefore, V_{CCIO} supplies should be powered up before or together with the V_{CC} and V_{CCAUX} supplies

Supported Standards

The MachXO sysIO buffer supports both single-ended and differential standards. Single-ended standards can be further subdivided into LVCMOS and LVTTL. The buffer supports the LVTTL, LVCMOS 1.2, 1.5, 1.8, 2.5, and 3.3V standards. In the LVCMOS and LVTTL modes, the buffer has individually configurable options for drive strength, bus maintenance (weak pull-up, weak pull-down, bus-keeper latch or none) and open drain. BLVDS and LVPECL output emulation is supported on all devices. The MachXO1200 and MachXO2280 support on-chip LVDS output buffers on approximately 50% of the I/Os on the left and right Banks. Differential receivers for LVDS, BLVDS and LVPECL are supported on all Banks of MachXO1200 and MachXO2280 devices. PCI support is provided in the top Banks of the MachXO1200 and MachXO2280 devices. Table 2-8 summarizes the I/O characteristics of the devices in the MachXO family.

Tables 2-9 and 2-10 show the I/O standards (together with their supply and reference voltages) supported by the MachXO devices. For further information on utilizing the sysIO buffer to support a variety of standards please see the details of additional technical documentation at the end of this data sheet.

Figure 2-20. MachXO640 Banks

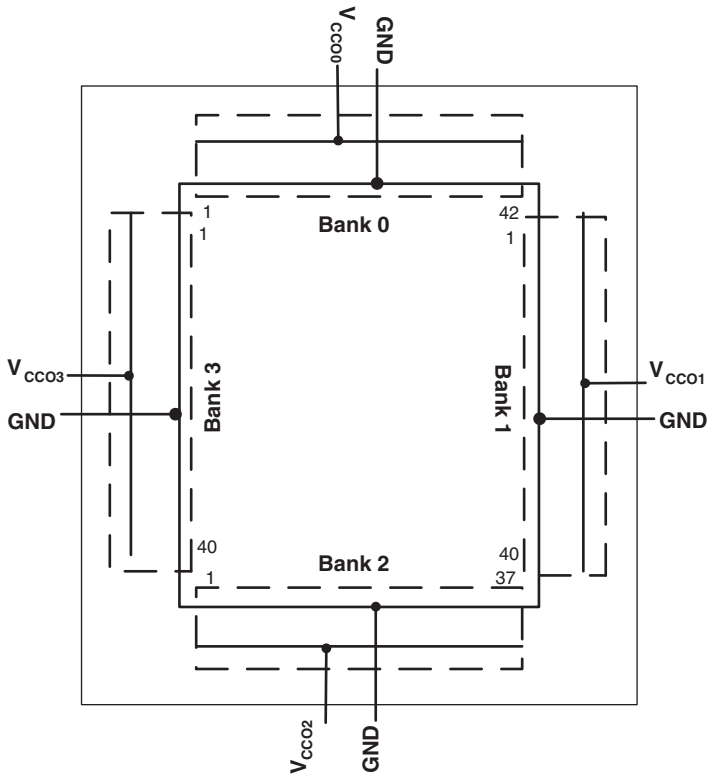
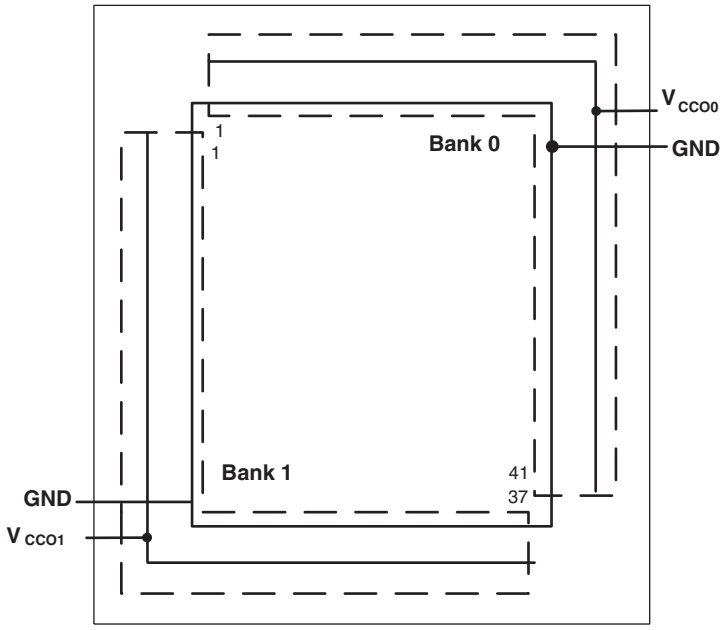


Figure 2-21. MachXO256 Banks



Hot Socketing

The MachXO devices have been carefully designed to ensure predictable behavior during power-up and power-down. Leakage into I/O pins is controlled to within specified limits. This allows for easy integration with the rest of

the system. These capabilities make the MachXO ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The MachXO "C" devices (V_{CC} = 1.8/2.5/3.3V) have a sleep mode that allows standby current to be reduced dramatically during periods of system inactivity. Entry and exit to Sleep mode is controlled by the SLEEPN pin.

During Sleep mode, the logic is non-operational, registers and EBR contents are not maintained, and I/Os are tri-stated. Do not enter Sleep mode during device programming or configuration operation. In Sleep mode, power supplies are in their normal operating range, eliminating the need for external switching of power supplies. Table 2-11 compares the characteristics of Normal, Off and Sleep modes.

Table 2-11. Characteristics of Normal, Off and Sleep Modes

Characteristic	Normal	Off	Sleep
SLEEPN Pin	High	—	Low
Static Icc	Typical <10mA	0	Typical <100uA
I/O Leakage	<10µA	<1mA	<10µA
Power Supplies VCC/VCCIO/VCCAUX	Normal Range	0	Normal Range
Logic Operation	User Defined	Non Operational	Non operational
I/O Operation	User Defined	Tri-state	Tri-state
JTAG and Programming circuitry	Operational	Non-operational	Non-operational
EBR Contents and Registers	Maintained	Non-maintained	Non-maintained

SLEEPN Pin Characteristics

The SLEEPN pin behaves as an LVCMOS input with the voltage standard appropriate to the VCC supply for the device. This pin also has a weak pull-up, along with a Schmidt trigger and glitch filter to prevent false triggering. An external pull-up to VCC is recommended when Sleep Mode is not used to ensure the device stays in normal operation mode. Typically, the device enters sleep mode several hundred nanoseconds after SLEEPN is held at a valid low and restarts normal operation as specified in the Sleep Mode Timing table. The AC and DC specifications portion of this data sheet shows a detailed timing diagram.

Oscillator

Every MachXO device has an internal CMOS oscillator. The oscillator can be routed as an input clock to the clock tree or to general routing resources. The oscillator frequency can be divided by internal logic. There is a dedicated programming bit to enable/disable the oscillator. The oscillator frequency ranges from 18MHz to 26MHz.

Configuration and Testing

The following section describes the configuration and testing features of the MachXO family of devices.

IEEE 1149.1-Compliant Boundary Scan Testability

All MachXO devices have boundary scan cells that are accessed through an IEEE 1149.1 compliant test access port (TAP). This allows functional testing of the circuit board, on which the device is mounted, through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test data to be captured and shifted out for verification. The test access port consists of dedicated I/Os: TDI, TDO, TCK and TMS. The test access port shares its power supply with one of the VCCIO Banks (MachXO256: V_{CCIO1}; MachXO640: V_{CCIO2}; MachXO1200 and MachXO2280: V_{CCIO5}) and can operate with LVCMOS3.3, 2.5, 1.8, 1.5, and 1.2 standards.

For more details on boundary scan test, please see information regarding additional technical documentation at the end of this data sheet.

Device Configuration

All MachXO devices contain a test access port that can be used for device configuration and programming.

The non-volatile memory in the MachXO can be configured in two different modes:

- In IEEE 1532 mode via the IEEE 1149.1 port. In this mode, the device is off-line and I/Os are controlled by BSCAN registers.
- In background mode via the IEEE 1149.1 port. This allows the device to remain operational in user mode while reprogramming takes place.

The SRAM configuration memory can be configured in three different ways:

- At power-up via the on-chip non-volatile memory.
- After a refresh command is issued via the IEEE 1149.1 port.
- In IEEE 1532 mode via the IEEE 1149.1 port.

Figure 2-22 provides a pictorial representation of the different programming modes available in the MachXO devices. On power-up, the SRAM is ready to be configured with IEEE 1149.1 serial TAP port using IEEE 1532 protocols.

Leave Alone I/O
When using IEEE 1532 mode for non-volatile memory programming, SRAM configuration, or issuing a refresh command, users may specify I/Os as high, low, tristated or held at current value. This provides excellent flexibility for implementing systems where reconfiguration or reprogramming occurs on-the-fly.

TransFR (Transparent Field Reconfiguration)
TransFR (TFR) is a unique Lattice technology that allows users to update their logic in the field without interrupting system operation using a single ispVM command. See TN1087, Minimizing System Interruption During Configuration Using TransFR Technology for details.

Security
The MachXO devices contain security bits that, when set, prevent the readback of the SRAM configuration and non-volatile memory spaces. Once set, the only way to clear the security bits is to erase the memory space.

For more information on device configuration, please see details of additional technical documentation at the end of this data sheet.

sysIO Recommended Operating Conditions

Standard	V_{CCIO} (V)		
	Min.	Typ.	Max.
LVCMOS 3.3	3.135	3.3	3.465
LVCMOS 2.5	2.375	2.5	2.625
LVCMOS 1.8	1.71	1.8	1.89
LVCMOS 1.5	1.425	1.5	1.575
LVCMOS 1.2	1.14	1.2	1.26
LVTTL	3.135	3.3	3.465
PCI[3]	3.135	3.3	3.465
LVDS[1, 2]	2.375	2.5	2.625
LVPECL[1]	3.135	3.3	3.465
BLVDS[1]	2.375	2.5	2.625
RSDS[1]	2.375	2.5	2.625

1. Inputs on chip. Outputs are implemented with the addition of external resistors.
2. MachXO1200 and MachXO2280 devices have dedicated LVDS buffers
3. Input on the top bank of the MachXO1200 and MachXO2280 only.

sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL}[1] (mA)	I_{OH}[1] (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	2.4	16	-16
					0.4	V_{CCIO} - 0.4	12, 8, 4	-12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	16, 12, 8, 4	-14, -12, -8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	V_{CCIO} - 0.4	8, 4	-8, -4
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 (“C” Version)	-0.3	0.42	0.78	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
LVCMOS 1.2 (“E” Version)	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	V_{CCIO} - 0.4	6, 2	-6, -2
					0.2	V_{CCIO} - 0.2	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O Bank and the end of an I/O Bank, as shown in the logic signal connections table shall not exceed n * 8mA. Where n is the number of I/Os between Bank GND connections or between the last GND in a Bank and the end of a Bank.

MachXO Family Timing Adders[1, 2, 3]

Over Recommended Operating Conditions

Buffer Type	Description	-5	-4	-3	Units
Input Adjusters					
LVDS25[4]	LVDS	0.44	0.53	0.61	ns
BLVDS25[4]	BLVDS	0.44	0.53	0.61	ns
LVPECL33[4]	LVPECL	0.42	0.50	0.59	ns
LVTTL33	LVTTL	0.01	0.01	0.01	ns
LVCMOS33	LVCMOS 3.3	0.01	0.01	0.01	ns
LVCMOS25	LVCMOS 2.5	0.00	0.00	0.00	ns
LVCMOS18	LVCMOS 1.8	0.07	0.08	0.10	ns
LVCMOS15	LVCMOS 1.5	0.14	0.17	0.19	ns
LVCMOS12	LVCMOS 1.2	0.40	0.48	0.56	ns
PCI33[4]	PCI	0.01	0.01	0.01	ns
Output Adjusters					
LVDS25E	LVDS 2.5 E	-0.13	-0.15	-0.18	ns
LVDS25[4]	LVDS 2.5	-0.21	-0.26	-0.30	ns
BLVDS25	BLVDS 2.5	-0.03	-0.03	-0.04	ns
LVPECL33	LVPECL 3.3	0.04	0.04	0.05	ns
LVTTL33_4mA	LVTTL 4mA drive	0.04	0.04	0.05	ns
LVTTL33_8mA	LVTTL 8mA drive	0.06	0.07	0.08	ns
LVTTL33_12mA	LVTTL 12mA drive	-0.01	-0.01	-0.01	ns
LVTTL33_16mA	LVTTL 16mA drive	0.50	0.60	0.70	ns
LVCMOS33_4mA	LVCMOS 3.3 4mA drive	0.04	0.04	0.05	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	0.06	0.07	0.08	ns
LVCMOS33_12mA	LVCMOS 3.3 12mA drive	-0.01	-0.01	-0.01	ns
LVCMOS33_14mA	LVCMOS 3.3 14mA drive	0.50	0.60	0.70	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	0.05	0.06	0.07	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0.10	0.12	0.13	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.00	0.00	0.00	ns
LVCMOS25_14mA	LVCMOS 2.5 14mA drive	0.34	0.40	0.47	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	0.11	0.13	0.15	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	0.05	0.06	0.06	ns
LVCMOS18_12mA	LVCMOS 1.8 12mA drive	-0.06	-0.07	-0.08	ns
LVCMOS18_14mA	LVCMOS 1.8 14mA drive	0.06	0.07	0.09	ns
LVCMOS15_4mA	LVCMOS 1.5 4mA drive	0.15	0.19	0.22	ns
LVCMOS15_8mA	LVCMOS 1.5 8mA drive	0.05	0.06	0.07	ns
LVCMOS12_2mA	LVCMOS 1.2 2mA drive	0.26	0.31	0.36	ns
LVCMOS12_6mA	LVCMOS 1.2 6mA drive	0.05	0.06	0.07	ns
PCI33[4]	PCI33	1.85	2.22	2.59	ns

1. Timing adders are characterized but not tested on every device.
2. LVCMOS timing is measured with the load specified in Switching Test Conditions table.
3. All other standards tested according to the appropriate specifications.
4. I/O standard only available in LCMXO1200 and LCMXO2280 devices.

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Signal Descriptions

Signal Name	I/O	Descriptions
General Purpose		
P[Edge] [Row/Column Number]_[A/B/C/D/E/F]	I/O	[Edge] indicates the edge of the device on which the pad is located. Valid edge designations are L (Left), B (Bottom), R (Right), T (Top). [Row/Column Number] indicates the PFU row or the column of the device on which the PIO Group exists. When Edge is T (Top) or (Bottom), only need to specify Row Number. When Edge is L (Left) or R (Right), only need to specify Column Number. [A/B/C/D/E/F] indicates the PIO within the group to which the pad is connected. Some of these user programmable pins are shared with special function pins. When not used as special function pins, these pins can be programmed as I/Os for user logic. During configuration of the user-programmable I/Os, the user has an option to tri-state the I/Os and enable an internal pull-up resistor. This option also applies to unused pins (or those not bonded to a package pin). The default during configuration is for user-programmable I/Os to be tri-stated with an internal pull-up resistor enabled. When the device is erased, I/Os will be tri-stated with an internal pull-up resistor enabled.
GSRN	I	Global RESET signal (active low). Dedicated pad, when not in use it can be used as an I/O pin.
TSALL	I	TSALL is a dedicated pad for the global output enable signal. When TSALL is high all the outputs are tristated. It is a dual function pin. When not in use, it can be used as an I/O pin.
NC	—	No connect.
GND	—	GND - Ground. Dedicated pins.
V_{CC}	—	VCC - The power supply pins for core logic. Dedicated pins.
V_{CCAUX}	—	VCCAUX - the Auxiliary power supply pin. This pin powers up a variety of internal circuits including all the differential and referenced input buffers. Dedicated pins.
V_{CCIOx}	—	V_{CCIO} - The power supply pins for I/O Bank x. Dedicated pins.
SLEEPN[1]	I	Sleep Mode pin - Active low sleep pin.þ When this pin is held high, the device operates normally.þ This pin has a weak internal pull-up, but when unused, an external pull-up to V_{CC} is recommended. When driven low, the device moves into Sleep mode after a specified time.
PLL and Clock Functions (Used as user programmable I/O pins when not used for PLL or clock pins)		
[LOC][0]_PLL[T, C]_IN	—	Reference clock (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
[LOC][0]_PLL[T, C]_FB	—	Optional feedback (PLL) input Pads: [LOC] indicates location. Valid designations are ULM (Upper PLL) and LLM (Lower PLL). T = true and C = complement.
PCLK [n]_[1:0]	—	Primary Clock Pads, n per side.
Test and Programming (Dedicated pins)		
TMS	I	Test Mode Select input pin, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data input pin, used to load data into the device using an 1149.1 state machine.
TDO	O	Output pin -Test Data output pin used to shift data out of the device using 1149.1.

1. Applies to MachXO “C” devices only. NC for “E” devices.

Power Supply and NC

Signal	100 TQFP[1]	144 TQFP[1]	100 csBGA[2]
VCC	**LCMXO256/640**: 35, 90 **LCMXO1200/2280**: 17, 35, 66, 91	21, 52, 93, 129	P7, B6
VCCIO0	**LCMXO256**: 60, 74, 92 **LCMXO640**: 80, 92 **LCMXO1200/2280**: 94	**LCMXO640**: 117, 135 **LCMXO1200/2280**: 135	**LCMXO256**: H14, A14, B5 **LCMXO640**: B12, B5
VCCIO1	**LCMXO256**: 10, 24, 41 **LCMXO640**: 60, 74 **LCMXO1200/2280**: 80	**LCMXO640**: 82, 98 **LCMXO1200/2280**: 117	**LCMXO256**: G1, P1, P10 **LCMXO640**: H14, A14
VCCIO2	**LCMXO256**: None **LCMXO640**: 29, 41 **LCMXO1200/2280**: 70	**LCMXO640**: 38, 63 **LCMXO1200/2280**: 98	**LCMXO256**: None **LCMXO640**: P4, P10
VCCIO3	**LCMXO256**: None **LCMXO640**: 10, 24 **LCMXO1200/2280**: 56	**LCMXO640**: 10, 26 **LCMXO1200/2280**: 82	**LCMXO256**: None **LCMXO640**: G1, P1
VCCIO4	**LCMXO256/640**: None **LCMXO1200/2280**: 44	**LCMXO640**: None **LCMXO1200/2280**: 63	—
VCCIO5	**LCMXO256/640**: None **LCMXO1200/2280**: 27	**LCMXO640**: None **LCMXO1200/2280**: 38	—
VCCIO6	**LCMXO256/640**: None **LCMXO1200/2280**: 20	**LCMXO640**: None **LCMXO1200/2280**: 26	—
VCCIO7	**LCMXO256/640**: None **LCMXO1200/2280**: 6	**LCMXO640**: None **LCMXO1200/2280**: 10	—
VCCAUX	**LCMXO256/640**: 88 **LCMXO1200/2280**: 36, 90	53, 128	B7
GND[3]	**LCMXO256**: 40, 84, 62, 75, 93, 12, 25, 42 **LCMXO640**: 40, 84, 81, 93, 62, 75, 30, 42, 12, 25 **LCMXO1200/2280**: 9, 41, 59, 83, 100, 76, 50, 26	16, 59, 88, 123, 118, 136, 83, 99, 37, 64, 11, 27	**LCMXO256**: N9, B9, G14, B13, A4, H1, N2, N10 **LCMXO640**: N9, B9, A10, A4, G14, B13, N3, N10, H1, N2
NC[4]			—

1. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.
2. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.
3. All grounds must be electrically connected at the board level. For fpBGA and ftBGA packages, the total number of GND balls is less than the actual number of GND logic connections from the die to the common package GND plane.
4. NC pins should not be connected to any active signals, VCC or GND.

LCMXO1200 and LCMXO2280 Logic Signal Connections: 100 TQFP

Pin Number	LCMXO1200				LCMXO2280			
	Ball Function	Bank	Dual Function	Differential	Ball Function	Bank	Dual Function	Differential
1	PL2A	7		T	PL2A	7	LUM0_PLLT_FB_A	T
2	PL2B	7		C	PL2B	7	LUM0_PLLC_FB_A	C
3	PL3C	7		T	PL3C	7	LUM0_PLLT_IN_A	T
4	PL3D	7		C	PL3D	7	LUM0_PLLC_IN_A	C
5	PL4B	7			PL4B	7		
6	VCCIO7	7			VCCIO7	7		
7	PL6A	7		T*	PL7A	7		T*
8	PL6B	7	GSRN	C*	PL7B	7	GSRN	C*
9	GND	-			GND	-		
10	PL7C	7		T	PL9C	7		T
11	PL7D	7		C	PL9D	7		C
12	PL8C	7		T	PL10C	7		T
13	PL8D	7		C	PL10D	7		C
14	PL9C	6			PL11C	6		
15	PL10A	6		T*	PL13A	6		T*
16	PL10B	6		C*	PL13B	6		C*
17	VCC	-			VCC	-		
18	PL11B	6			PL14D	6		C
19	PL11C	6	TSALL		PL14C	6	TSALL	T
20	VCCIO6	6			VCCIO6	6		
21	PL13C	6			PL16C	6		
22	PL14A	6	LLM0_PLLT_FB_A	T*	PL17A	6	LLM0_PLLT_FB_A	T*
23	PL14B	6	LLM0_PLLC_FB_A	C*	PL17B	6	LLM0_PLLC_FB_A	C*
24	PL15A	6	LLM0_PLLT_IN_A	T*	PL18A	6	LLM0_PLLT_IN_A	T*
25	PL15B	6	LLM0_PLLC_IN_A	C*	PL18B	6	LLM0_PLLC_IN_A	C*
26**	GNDIO6 GNDIO5	-			GNDIO6 GNDIO5	-		
27	VCCIO5	5			VCCIO5	5		
28	TMS	5	TMS		TMS	5	TMS	
29	TCK	5	TCK		TCK	5	TCK	
30	PB3B	5			PB3B	5		
31	PB4A	5		T	PB4A	5		T
32	PB4B	5		C	PB4B	5		C
33	TDO	5	TDO		TDO	5	TDO	
34	TDI	5	TDI		TDI	5	TDI	
35	VCC	-			VCC	-		
36	VCCAUX	-			VCCAUX	-		
37	PB6E	5		T	PB8E	5		T
38	PB6F	5		C	PB8F	5		C
39	PB7B	4	PCLK4_1****		PB10F	4	PCLK4_1****	
40	PB7F	4	PCLK4_0****		PB10B	4	PCLK4_0****	
41	GND	-			GND	-		

LCMXO256 and LCMXO640 Logic Signal Connections: 100 csBGA (Cont.)

LCMXO256					LCMXO640				
Ball Number	Ball Function	Bank	Dual Function	Differen-tial	Ball Number	Ball Function	Bank	Dual Function	Differen-tial
A4	GNDIO0	0			A4	GNDIO0	0		
B4	PT3A	0		T	B4	PT3B	0		C
A3	PT2F	0		C	A3	PT3A	0		T
B3	PT2E	0		T	B3	PT2F	0		C
A2	PT2D	0		C	A2	PT2E	0		T
C3	PT2C	0		T	C3	PT2B	0		C
A1	PT2B	0		C	A1	PT2C	0		
B2	PT2A	0		T	B2	PT2A	0		T
N9	GND	-			N9	GND	-		
B9	GND	-			B9	GND	-		
B5	VCCIO0	0			B5	VCCIO0	0		
A14	VCCIO0	0			A14	VCCIO1	1		
H14	VCCIO0	0			H14	VCCIO1	1		
P10	VCCIO1	1			P10	VCCIO2	2		
G1	VCCIO1	1			G1	VCCIO3	3		
P1	VCCIO1	1			P1	VCCIO3	3		

*NC for “E” devices.
**Primary clock inputs are single-ended.

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 132 csBGA

LCMXO640					LCMXO1200					LCMXO2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
B1	PL2A	3		T	B1	PL2A	7		T	B1	PL2A	7	LUM0_PLLT_FB_A	T
C1	PL2B	3		C	C1	PL3C	7		T	C1	PL3C	7	LUM0_PLLT_IN_A	T
B2	PL2C	3		T	B2	PL2B	7		C	B2	PL2B	7	LUM0_PLLC_FB_A	C
C2	PL2D	3		C	C2	PL4A	7		T*	C2	PL4A	7		T*
C3	PL3A	3		T	C3	PL3D	7		C	C3	PL3D	7	LUM0_PLLC_IN_A	C
D1	PL3B	3		C	D1	PL4B	7		C*	D1	PL4B	7		C*
D3	PL3D	3			D3	PL4C	7			D3	PL4C	7		
E1	GNDIO3	3			E1	GNDIO7	7			E1	GNDIO7	7		
E2	PL5A	3		T	E2	PL6A	7		T*	E2	PL7A	7		T*
E3	PL5B	3	GSRN	C	E3	PL6B	7	GSRN	C*	E3	PL7B	7	GSRN	C*
F2	PL5D	3			F2	PL6D	7			F2	PL7D	7		
F3	PL6B	3			F3	PL7C	7		T	F3	PL9C	7		T
G1	PL6C	3		T	G1	PL7D	7		C	G1	PL9D	7		C
G2	PL6D	3		C	G2	PL8C	7		T	G2	PL10C	7		T
G3	PL7A	3		T	G3	PL8D	7		C	G3	PL10D	7		C
H2	PL7B	3		C	H2	PL10A	6		T*	H2	PL12A	6		T*
H1	PL7C	3			H1	PL10B	6		C*	H1	PL12B	6		C*
H3	VCC	-			H3	VCC	-			H3	VCC	-		
J1	PL8A	3			J1	PL11B	6			J1	PL14D	6		C
J2	PL8C	3	TSALL		J2	PL11C	6	TSALL	T	J2	PL14C	6	TSALL	T
J3	PL9A	3		T	J3	PL11D	6		C	J3	PL14B	6		
K2	PL9B	3		C	K2	PL12A	6		T*	K2	PL15A	6		T*
K1	PL9C	3			K1	PL12B	6		C*	K1	PL15B	6		C*
L2	GNDIO3	3			L2	GNDIO6	6			L2	GNDIO6	6		
L1	PL10A	3		T	L1	PL14A	6	LLM0_PLLT_FB_A	T*	L1	PL17A	6	LLM0_PLLT_FB_A	T*
L3	PL10B	3		C	L3	PL14B	6	LLM0_PLLC_FB_A	C*	L3	PL17B	6	LLM0_PLLC_FB_A	C*
M1	PL11A	3		T	M1	PL15A	6	LLM0_PLLT_IN_A	T*	M1	PL18A	6	LLM0_PLLT_IN_A	T*
N1	PL11B	3		C	N1	PL16A	6		T	N1	PL19A	6		T
M2	PL11C	3		T	M2	PL15B	6	LLM0_PLLC_IN_A	C*	M2	PL18B	6	LLM0_PLLC_IN_A	C*
P1	PL11D	3		C	P1	PL16B	6		C	P1	PL19B	6		C
P2	GNDIO2	2			P2	GNDIO5	5			P2	GNDIO5	5		
P3	TMS	2	TMS		P3	TMS	5	TMS		P3	TMS	5	TMS	
M3	PB2C	2		T	M3	PB2C	5		T	M3	PB2A	5		T
N3	PB2D	2		C	N3	PB2D	5		C	N3	PB2B	5		C
P4	TCK	2	TCK		P4	TCK	5	TCK		P4	TCK	5	TCK	
M4	PB3B	2			M4	PB3B	5			M4	PB3B	5		
N4	PB3C	2		T	N4	PB4A	5		T	N4	PB4A	5		T
P5	PB3D	2		C	P5	PB4B	5		C	P5	PB4B	5		C
N5	TDO	2	TDO		N5	TDO	5	TDO		N5	TDO	5	TDO	
M5	TDI	2	TDI		M5	TDI	5	TDI		M5	TDI	5	TDI	
N6	PB4E	2		T	N6	PB5C	5			N6	PB6C	5		
P6	VCC	-			P6	VCC	-			P6	VCC	-		
M6	PB4F	2		C	M6	PB6A	5			M6	PB8A	5		
P7	VCCAUX	-			P7	VCCAUX	-			P7	VCCAUX	-		
N7	PB5A	2		T	N7	PB6F	5			N7	PB8F	5		
M7	PB5B	2	PCLK2_1***	C	M7	PB7B	4	PCLK4_1***		M7	PB10F	4	PCLK4_1***	
N8	PB5D	2			N8	PB7C	4		T	N8	PB10C	4		T
P8	PB6A	2		T	P8	PB7D	4		C	P8	PB10D	4		C
M8	PB6B	2	PCLK2_0***	C	M8	PB7F	4	PCLK4_0***		M8	PB10B	4	PCLK4_0***	
N9	PB7A	2		T	N9	PB9A	4		T	N9	PB12A	4		T

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 132 csBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
M9	PB7B	2		C	M9	PB9B	4		C	M9	PB12B	4		C
N10	PB7E	2		T	N10	PB9C	4		T	N10	PB12C	4		T
P10	PB7F	2		C	P10	PB9D	4		C	P10	PB12D	4		C
N11	GNDIO2	2			N11	GNDIO4	4			N11	GNDIO4	4		
P11	PB8C	2		T	P11	PB10A	4		T	P11	PB13C	4		T
M11	PB8D	2		C	M11	PB10B	4		C	M11	PB13D	4		C
P12	PB9C	2		T	P12	PB10C	4			P12	PB15B	4		
P13	PB9D	2		C	P13	PB11C	4		T	P13	PB16C	4		T
N12**	SLEEPN	-	SLEEPN		N12**	SLEEPN	-	SLEEPN		N12**	SLEEPN	-	SLEEPN	
P14	PB9F	2			P14	PB11D	4		C	P14	PB16D	4		C
N14	PR11D	1		C	N14	PR16B	3		C	N14	PR19B	3		C
M14	PR11C	1		T	M14	PR15B	3		C*	M14	PR18B	3		C*
N13	PR11B	1		C	N13	PR16A	3		T	N13	PR19A	3		T
M12	PR11A	1		T	M12	PR15A	3		T*	M12	PR18A	3		T*
M13	PR10B	1		C	M13	PR14B	3		C*	M13	PR17B	3		C*
L14	PR10A	1		T	L14	PR14A	3		T*	L14	PR17A	3		T*
L13	GNDIO1	1			L13	GNDIO3	3			L13	GNDIO3	3		
K14	PR8D	1		C	K14	PR12B	3		C*	K14	PR15B	3		C*
K13	PR8C	1		T	K13	PR12A	3		T*	K13	PR15A	3		T*
K12	PR8B	1		C	K12	PR11B	3		C*	K12	PR14B	3		C*
J13	PR8A	1		T	J13	PR11A	3		T*	J13	PR14A	3		T*
J12	PR7C	1			J12	PR10B	3		C*	J12	PR13B	3		C*
H14	PR7B	1		C	H14	PR10A	3		T*	H14	PR13A	3		T*
H13	PR7A	1		T	H13	PR9B	3		C*	H13	PR11B	3		C*
H12	PR6D	1		C	H12	PR9A	3		T*	H12	PR11A	3		T*
G13	PR6C	1		T	G13	PR8B	2		C*	G13	PR10B	2		C*
G14	PR6B	1			G14	PR8A	2		T*	G14	PR10A	2		T*
G12	VCC	-			G12	VCC	-			G12	VCC	-		
F14	PR5D	1		C	F14	PR6C	2			F14	PR8C	2		
F13	PR5C	1		T	F13	PR6B	2		C*	F13	PR8B	2		C*
F12	PR4D	1		C	F12	PR6A	2		T*	F12	PR8A	2		T*
E13	PR4C	1		T	E13	PR5B	2		C*	E13	PR7B	2		C*
E14	PR4B	1			E14	PR5A	2		T*	E14	PR7A	2		T*
D13	GNDIO1	1			D13	GNDIO2	2			D13	GNDIO2	2		
D14	PR3D	1		C	D14	PR4B	2		C*	D14	PR5B	2		C*
D12	PR3C	1		T	D12	PR4A	2		T*	D12	PR5A	2		T*
C14	PR2D	1		C	C14	PR3D	2		C	C14	PR4D	2		C
B14	PR2C	1		T	B14	PR2B	2		C	B14	PR3B	2		C*
C13	PR2B	1		C	C13	PR3C	2		T	C13	PR4C	2		T
A14	PR2A	1		T	A14	PR2A	2		T	A14	PR3A	2		T*
A13	PT9F	0		C	A13	PT11D	1		C	A13	PT16D	1		C
A12	PT9E	0		T	A12	PT11B	1		C	A12	PT16B	1		C
B13	PT9D	0		C	B13	PT11C	1		T	B13	PT16C	1		T
B12	PT9C	0		T	B12	PT10F	1			B12	PT15D	1		
C12	PT9B	0		C	C12	PT11A	1		T	C12	PT16A	1		T
A11	PT9A	0		T	A11	PT10D	1		C	A11	PT14B	1		C
C11	PT8C	0			C11	PT10C	1		T	C11	PT14A	1		T
A10	GNDIO0	0			A10	GNDIO1	1			A10	GNDIO1	1		
B10	PT7F	0		C	B10	PT9F	1		C	B10	PT12F	1		C
C10	PT7E	0		T	C10	PT9E	1		T	C10	PT12E	1		T

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 132 csBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential	Ball #	Ball Function	Bank	Dual Function	Differential
B9	PT7B	0		C	B9	PT9B	1		C	B9	PT12D	1		C
A9	PT7A	0		T	A9	PT9A	1		T	A9	PT12C	1		T
A8	PT6B	0	PCLK0_1***	C	A8	PT7D	1	PCLK1_1***		A8	PT10B	1	PCLK1_1***	
B8	PT6A	0		T	B8	PT7B	1			B8	PT9D	1		
C8	PT5B	0	PCLK0_0***	C	C8	PT6F	0	PCLK1_0***		C8	PT9B	1	PCLK1_0***	
B7	PT5A	0		T	B7	PT6D	0			B7	PT8D	0		
A7	VCCAUX	-			A7	VCCAUX	-			A7	VCCAUX	-		
C7	VCC	-			C7	VCC	-			C7	VCC	-		
A6	PT4D	0		C	A6	PT5D	0		C	A6	PT7B	0		C
B6	PT4C	0		T	B6	PT5C	0		T	B6	PT7A	0		T
C6	PT3F	0		C	C6	PT5B	0		C	C6	PT6D	0		
B5	PT3E	0		T	B5	PT5A	0		T	B5	PT6E	0		T
A5	PT3D	0			A5	PT4B	0			A5	PT6F	0		C
B4	GNDIO0	0			B4	GNDIO0	0			B4	GNDIO0	0		
A4	PT3B	0			A4	PT3D	0		C	A4	PT4B	0		C
C4	PT2F	0			C4	PT3C	0		T	C4	PT4A	0		T
A3	PT2D	0		C	A3	PT3B	0		C	A3	PT3B	0		C
A2	PT2C	0		T	A2	PT2B	0		C	A2	PT2B	0		C
B3	PT2B	0		C	B3	PT3A	0		T	B3	PT3A	0		T
A1	PT2A	0		T	A1	PT2A	0		T	A1	PT2A	0		T
F1	GND	-			F1	GND	-			F1	GND	-		
P9	GND	-			P9	GND	-			P9	GND	-		
J14	GND	-			J14	GND	-			J14	GND	-		
C9	GND	-			C9	GND	-			C9	GND	-		
C5	VCCIO0	0			C5	VCCIO0	0			C5	VCCIO0	0		
B11	VCCIO0	0			B11	VCCIO1	1			B11	VCCIO1	1		
E12	VCCIO1	1			E12	VCCIO2	2			E12	VCCIO2	2		
L12	VCCIO1	1			L12	VCCIO3	3			L12	VCCIO3	3		
M10	VCCIO2	2			M10	VCCIO4	4			M10	VCCIO4	4		
N2	VCCIO2	2			N2	VCCIO5	5			N2	VCCIO5	5		
D2	VCCIO3	3			D2	VCCIO7	7			D2	VCCIO7	7		
K3	VCCIO3	3			K3	VCCIO6	6			K3	VCCIO6	6		

*Supports true LVDS outputs.
**NC for “E” devices.
***Primary clock inputs arer single-ended.

LCMXO640, LCMXO1200 and LCMXO2280 Logic Signal Connections: 256 caBGA / 256 ftBGA (Cont.)

LCMXO640					LCMXO1200					LCMXO2280				
Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential	Ball Number	Ball Function	Bank	Dual Function	Differential
J13	PR8C	1		T	J13	PR11A	3		T*	J13	PR14A	3		T*
GND	GND	-			GND	GND	-			GND	GND	-		
K14	PR8B	1		C	K14	PR10D	3		C	K14	PR13D	3		C
J14	PR8A	1		T	J14	PR10C	3		T	J14	PR13C	3		T
K15	PR7D	1		C	K15	PR10B	3		C*	K15	PR13B	3		C*
J15	PR7C	1		T	J15	PR10A	3		T*	J15	PR13A	3		T*
-	-				GND	GNDIO3	3			GND	GNDIO3	3		
-	-				VCCIO3	VCCIO3	3			VCCIO3	VCCIO3	3		
K12	NC				K12	PR9D	3		C	K12	PR11D	3		C
J12	NC				J12	PR9C	3		T	J12	PR11C	3		T
J16	PR7B	1		C	J16	PR9B	3		C*	J16	PR11B	3		C*
H16	PR7A	1		T	H16	PR9A	3		T*	H16	PR11A	3		T*
H15	PR6B	1		C	H15	PR8D	2		C	H15	PR10D	2		C
G15	PR6A	1		T	G15	PR8C	2		T	G15	PR10C	2		T
H14	PR5D	1		C	H14	PR8B	2		C*	H14	PR10B	2		C*
G14	PR5C	1		T	G14	PR8A	2		T*	G14	PR10A	2		T*
GND	GNDIO1	1			GND	GNDIO2	2			GND	GNDIO2	2		
VCCIO1	VCCIO1	1			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
H13	PR6D	1		C	H13	PR7D	2		C	H13	PR9D	2		C
H12	PR6C	1		T	H12	PR7C	2		T	H12	PR9C	2		T
G13	PR4D	1		C	G13	PR7B	2		C*	G13	PR9B	2		C*
G12	PR4C	1		T	G12	PR7A	2		T*	G12	PR9A	2		T*
G16	PR5B	1		C	G16	PR6D	2		C	G16	PR7D	2		C
F16	PR5A	1		T	F16	PR6C	2		T	F16	PR7C	2		T
F15	PR4B	1		C	F15	PR6B	2		C*	F15	PR7B	2		C*
E15	PR4A	1		T	E15	PR6A	2		T*	E15	PR7A	2		T*
E16	PR3B	1		C	E16	PR5D	2		C	E16	PR6D	2		C
D16	PR3A	1		T	D16	PR5C	2		T	D16	PR6C	2		T
VCCIO1	VCCIO1	1			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
GND	GNDIO1	1			GND	GNDIO2	2			GND	GNDIO2	2		
D15	PR2D	1		C	D15	PR5B	2		C*	D15	PR6B	2		C*
C15	PR2C	1		T	C15	PR5A	2		T*	C15	PR6A	2		T*
C16	PR2B	1		C	C16	PR4D	2		C	C16	PR5D	2		C
B16	PR2A	1		T	B16	PR4C	2		T	B16	PR5C	2		T
F14	PR3D	1		C	F14	PR4B	2		C*	F14	PR5B	2		C*
E14	PR3C	1		T	E14	PR4A	2		T*	E14	PR5A	2		T*
-	-	-			-	-	-			GND	GND	-		
F12	NC				F12	PR3D	2		C	F12	PR4D	2		C
F13	NC				F13	PR3C	2		T	F13	PR4C	2		T
E12	NC				E12	PR3B	2		C*	E12	PR4B	2		C*
E13	NC				E13	PR3A	2		T*	E13	PR4A	2		T*
D13	NC				D13	PR2B	2		C	D13	PR3B	2		C*
D14	NC				D14	PR2A	2		T	D14	PR3A	2		T*
VCCIO0	VCCIO0	0			VCCIO2	VCCIO2	2			VCCIO2	VCCIO2	2		
GND	GNDIO0	0			GND	GNDIO2	2			GND	GNDIO2	2		
GND	GNDIO0	0			GND	GNDIO1	1			GND	GNDIO1	1		
VCCIO0	VCCIO0	0			VCCIO1	VCCIO1	1			VCCIO1	VCCIO1	1		
B15	NC				B15	PT11D	1		C	B15	PT16D	1		C
A15	NC				A15	PT11C	1		T	A15	PT16C	1		T
C14	NC				C14	PT11B	1		C	C14	PT16B	1		C
B14	NC				B14	PT11A	1		T	B14	PT16A	1		T
C13	PT9F	0		C	C13	PT10F	1		C	C13	PT15D	1		C
B13	PT9E	0		T	B13	PT10E	1		T	B13	PT15C	1		T

LCMXO2280 Logic Signal Connections: 324 ftBGA (Cont.)

LCMXO2280				
Ball Number	**Ball Function**	**Bank**	**Dual Function**	**Differential**
A10	PT8E	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
A9	PT8D	0		C
C9	PT8C	0		T
B9	PT8B	0		C
F9	VCCAUX	-		
A8	PT8A	0		T
B8	PT7D	0		C
C8	PT7C	0		T
VCC	VCC	-		
A7	PT7B	0		C
B7	PT7A	0		T
A6	PT6A	0		T
B6	PT6B	0		C
D8	PT6C	0		T
F8	PT6D	0		C
C7	PT6E	0		T
E8	PT6F	0		C
D7	PT5D	0		C
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E7	PT5C	0		T
A5	PT5B	0		C
C6	PT5A	0		T
B5	PT4A	0		T
A4	PT4B	0		C
D6	PT4C	0		T
F7	PT4D	0		C
B4	PT4E	0		T
GND	GND	-		
C5	PT4F	0		C
F6	PT3D	0		C
E5	PT3C	0		T
E6	PT3B	0		C
D5	PT3A	0		T
A3	PT2D	0		C
C4	PT2C	0		T
A2	PT2B	0		C
B2	PT2A	0		T
VCCIO0	VCCIO0	0		
GND	GNDIO0	0		
E14	GND	-		

MachXO Family Data Sheet Ordering Information

June 2013 Data Sheet DS1002

Part Number Description

LCMXO XXXX X – X XXXXXX X XX

Device Family
MachXO PLD

Logic Capacity
256 LUTs = 256
640 LUTs = 640
1200 LUTs = 1200
2280 LUTs = 2280

Supply Voltage
C = 1.8V/2.5V/3.3V
E = 1.2V

Note: Parts dual marked as described.

Speed
3 = Slowest
4
5 = Fastest

Package
T100 = 100-pin TQFP
T144 = 144-pin TQFP
M100 = 100-ball csBGA
M132 = 132-ball csBGA
B256 = 256-ball caBGA
FT256 = 256-ball ftBGA
FT324 = 324-ball ftBGA

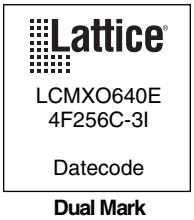
TN100 = 100-pin Lead-Free TQFP
TN144 = 144-pin Lead-Free TQFP
MN100 = 100-ball Lead-Free csBGA
MN132 = 132-ball Lead-Free csBGA
BN256 = 256-ball Lead-Free caBGA
FTN256 = 256-ball Lead-Free ftBGA
FTN324 = 324-ball Lead-Free ftBGA

Grade
C = Commercial
I = Industrial

ES = Engineering Sample
Blank = Production Device

Ordering Information

Note: MachXO devices are dual marked except the slowest commercial speed grade device.þFor example the commercial speed grade LCMXO640E-4F256C is also marked with industrial grade -3I grade.þThe slowest commercial speed grade does not have industrial markings.þ The markings appears as follows:



Dual Mark

MachXO Family Data Sheet Supplemental Information

For Further Information

A variety of technical notes for the MachXO family are available on the Lattice web site.

- TN1091, MachXO sysIO Usage Guide
- TN1089, MachXO sysCLOCK Design and Usage Guide
- TN1092, Memory Usage Guide for MachXO Devices
- TN1090, Power Estimation and Management for MachXO Devices
- TN1086, MachXO JTAG Programming and Configuration User's Guide
- TN1087, Minimizing System Interruption During Configuration Using TransFR Technology
- TN1097, MachXO Density Migration
- AN8066, Boundary Scan Testability with Lattice sysIO Capability

For further information on interface standards refer to the following web sites:

- JEDEC Standards (LVTTL, LVCMOS): www.jedec.org
- PCI: www.pcisig.com

Date	Version	Section	Change Summary
April 2006 (cont.)	02.0 (cont.)	Architecture (cont.)	"Top View of the MachXO1200 Device" figure updated.
			"Top View of the MachXO640 Device" figure updated.
			"Top View of the MachXO256 Device" figure updated.
			"Slice Diagram" figure updated.
			Slice Signal Descriptions table updated.
			Routing section updated.
			sysCLOCK Phase Lockecd Loops (PLLs) section updated.
			PLL Diagram updated.
			PLL Signal Descriptions table updated.
			sysMEM Memory section has been updated.
			PIO Groups section has been updated.
			PIO section has been updated.
			MachXO PIO Block Diagram updated.
			Supported Input Standards table updated.
			MachXO Configuration and Programming diagram updated.
		DC and Switching Characteristics	Recommended Operating Conditions table - footnotes updated.
			MachXO256 and MachXO640 Hot Socketing Specifications - footnotes updated.
			Added MachXO1200 and MachXO2280 Hot Socketing Specifications table.
			DC Electrical Characteristics, footnotes have been updated.
			Supply Current (Sleep Mode) table has been updated, removed "4W" references. Footnotes have been updated.
			Supply Current (Standby) table and associated footnotes updated.
			Intialization Supply Current table and footnotes updated.
			Programming and Erase Flash Supply Current table and associated footnotes have been updatd.
			Register-to-Register Performance table updated (rev. A 0.19).
			MachXO External Switching Characteristics updated (rev. A 0.19).
			MachXO Internal Timing Parameters updated (rev. A 0.19).
			MachXO Family Timing Adders updated (rev. A 0.19).
			sysCLOCK Timing updated (rev. A 0.19).
			MachXO "C" Sleep Mode Timing updated (A 0.19).
			JTAG Port Timing Specification updated (rev. A 0.19).
			Test Fixture Required Components table updated.
		Pinout Information	Signal Descriptions have been updated.
			Pin Information Summary has been updated. Footnote has been added.
			Power Supply and NC Connection table has been updated.
			Logic Signal Connections have been updated (PCLKTx_x --> PCLKx_x)
		Ordering Information	Removed "4W" references.
			Added 256-ftBGA Ordering Part Numbers for MachXO640.
May 2006	02.1	Pinout Information	Removed [LOC][0]_PLL_RST from Signal Description table.
			PCLK footnote has been added to all appropriate pins.
August 2006	02.2	Multiple	Removed 256 fpBGA information for MachXO640.